

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A substrate to mount a die having a plurality of terminals, the substrate comprising:

a dielectric core member;

a first plurality of dielectric lamination layers on a first side of the core member;

a second plurality of conductive layers on the first side of the core member, including a plurality of ball-grid array (BGA) connectors on a first surface of an uppermost one of the second plurality of conductive layers to couple to corresponding terminals of the die;

~~a first number of dielectric lamination layers on a second side of the core member, wherein the first number is less than the first plurality; and~~

a single conductive layer ~~second number of conductive layers~~ on the second side of the core member, wherein the single conductive layer comprises a plurality of lands ~~second number is less than the second plurality; and~~

a plurality of solder balls, coupled to corresponding ones of the plurality of lands, to couple to corresponding terminals of a receiving substrate.

2. (Previously Presented) A substrate as claimed in claim 1 wherein the dielectric core member comprises material of different dielectric permittivity in comparison to a permittivity of material of dielectric lamination layers of the substrate.

3. (Previously Presented) A substrate as claimed in claim 1, wherein the dielectric core member has a thickness that is thicker than a thickness of at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than that of material of the at least one dielectric lamination layer.

4-7. (Canceled)

8. (Currently Amended) A system comprising:
a die having a plurality of terminals;
a receiving substrate having a plurality of terminals;
a layered substrate including
 a dielectric core member;
 a first plurality of dielectric lamination layers on a first side of the core member;
 a second plurality of conductive layers on the first side of the core member,
including a plurality of ball-grid array connectors on a first surface of an uppermost one
of the second plurality of conductive layers, the connectors being coupled to
corresponding terminals of the die;
~~a first number of dielectric lamination layers on a second side of the core member,~~
~~wherein the first number is less than the first plurality; and~~
 a single conductive layer ~~second number of conductive layers~~ on the second side
of the core member, wherein the single conductive layer comprises a plurality of lands
~~second number is less than the second plurality; and~~
 a plurality of solder balls, coupled between ones of the plurality of lands and
corresponding terminals of the receiving substrate.
9. (Previously Presented) A system as claimed in claim 8, wherein the dielectric core member comprises material of a different dielectric permittivity in comparison to a permittivity of material of dielectric lamination layers of the substrate.
10. (Currently Amended) A system as claimed in claim 8, wherein the dielectric core member has a thickness that is thicker than a thickness of at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than that of a material of the at least one dielectric lamination layer[[],].
- 11-25. (Canceled)

26. (New) The substrate as claimed in claim 1, wherein the receiving substrate comprises one of an interposer or a motherboard.

27. (New) The system as claimed in claim 8, wherein the receiving substrate comprises one of an interposer or a motherboard.